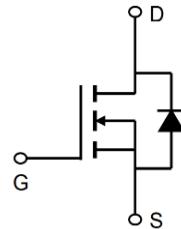


## Description

The AP200N10MP uses advanced **SGT<sub>II</sub>** technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.



## General Features

$V_{DS} = 100V$   $I_D = 200A$

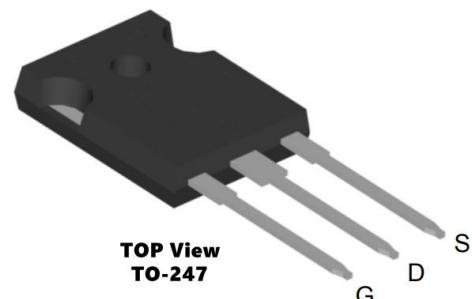
$R_{DS(ON)} < 5.0m\Omega$  @  $V_{GS}=10V$  (**Type: 4.1mΩ**)

## Application

DC/DC Converter

LED Backlighting

Power Management Switches



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP200N10MP	TO-247-3L	AP200N10MP XXX YYYY	300

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS}$ @ 10V	200	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS}$ @ 10V	125	A
$I_{DM}$	Pulsed Drain Current	580	A
$E_{AS}$	Single Pulse Avalanche Energy	540	mJ
$I_{AS}$	Avalanche Current	53.4	A
$P_D@T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	148	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	0.42	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	40	°C/W



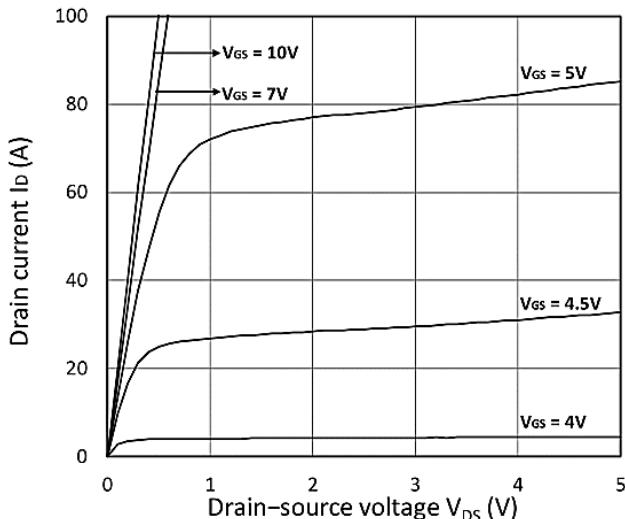
**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	100	107	-	V
IGSS	Gate-body Leakage current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
IDSS	Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$
	Zero Gate Voltage Drain Current $T_J=100^\circ\text{C}$		-	-	100	
VGS(th)	Gate-Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	3.0	4.0	V
RDS(on)	Drain-Source on-Resistance <sup>4</sup>	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	4.1	5.0	$\text{m}\Omega$
gfs	Forward Transconductance <sup>4</sup>	$V_{DS} = 10\text{V}, I_D = 20\text{A}$	-	62	-	S
Ciss	Input Capacitance	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	6865	-	$\text{pF}$
Coss	Output Capacitance		-	740	-	
Crss	Reverse Transfer Capacitance		-	21	-	
R <sub>g</sub>	Gate Resistance	f = 1MHz	-	1.3	-	$\Omega$
Q <sub>g</sub>	Total Gate Charge	$V_{GS} = 10\text{V}, V_{DS} = 50\text{V}, I_D = 20\text{A}$	-	111.2	-	$\text{nC}$
Q <sub>gs</sub>	Gate-Source Charge		-	30.5	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	27.3	-	
td(on)	Turn-on Delay Time	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	33	-	$\text{ns}$
t <sub>r</sub>	Rise Time		-	39	-	
td(off)	Turn-off Delay Time		-	67.1	-	
t <sub>f</sub>	Fall Time		-	32	-	
trr	Body Diode Reverse Recovery Time	$I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	58.7	-	$\text{ns}$
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	97.3	-	$\text{nC}$
VSD	Diode Forward Voltage <sup>4</sup>	$I_S = 20\text{A}, V_{GS} = 0\text{V}$	-	-	1.2	V
IS	Continuous Source Current $T_c=25^\circ\text{C}$	-	-	-	120	A

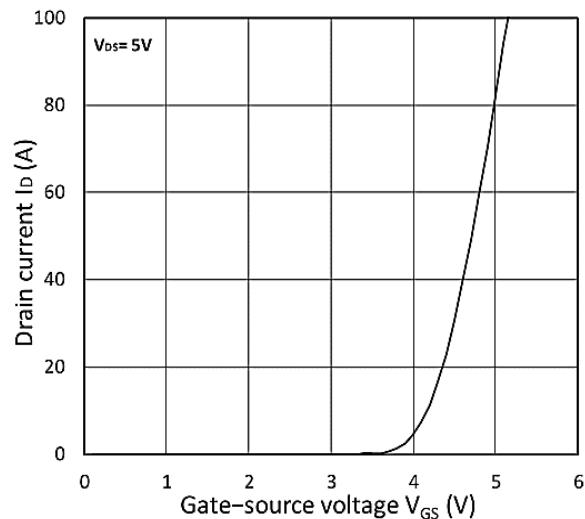
**Notes:**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  $V_{DD}=50\text{V}, V_{GS}=10\text{V}, L=0.4\text{mH}, I_{AS}=32\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

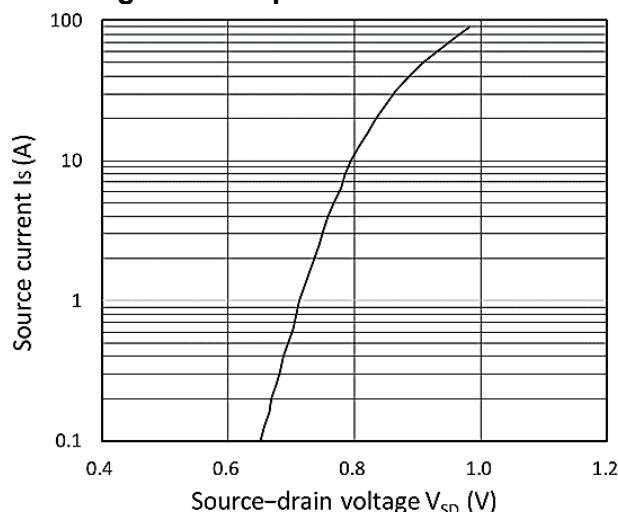
## Typical Characteristics



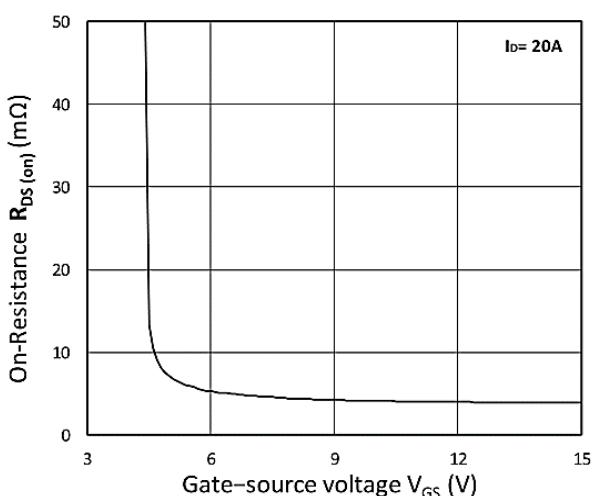
**Figure 1. Output Characteristics**



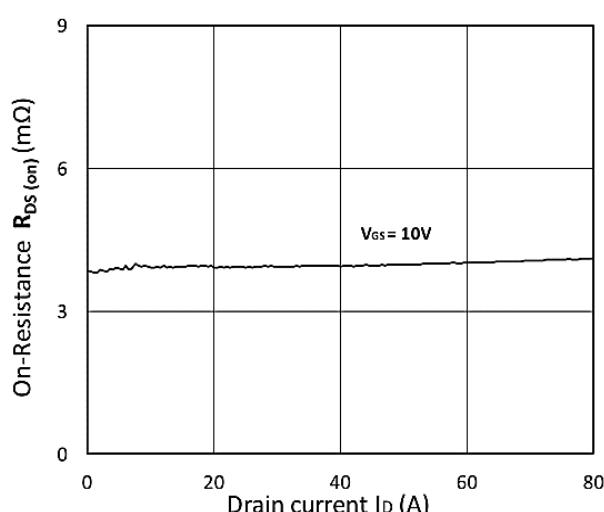
**Figure 2. Transfer Characteristics**



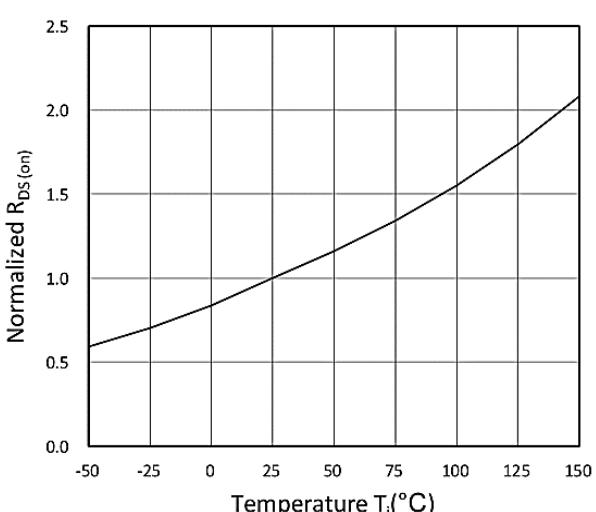
**Figure 3. Forward Characteristics of Reverse**



**Figure 4. RDS(ON) vs. VGS**



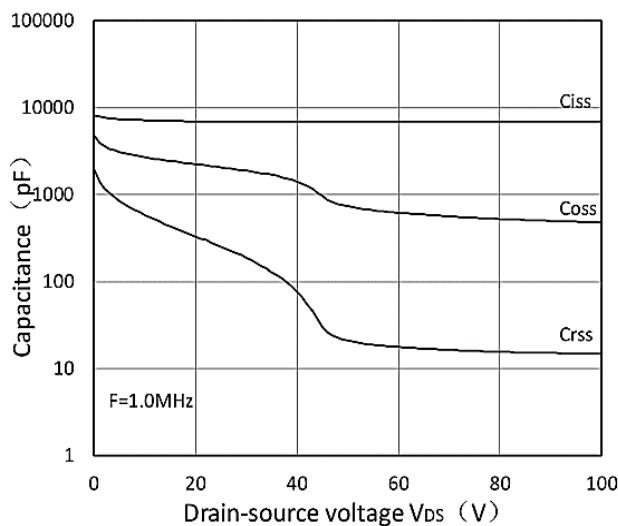
**Figure 5. RDS(ON) vs. ID**



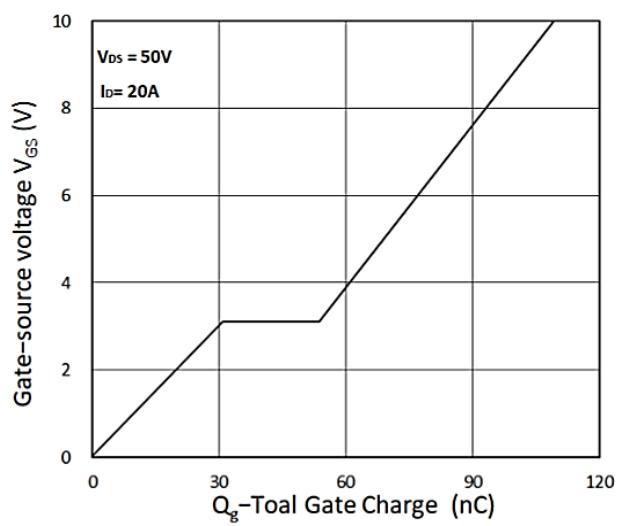
**Figure 6. Normalized RDS(on) vs. Temperature**



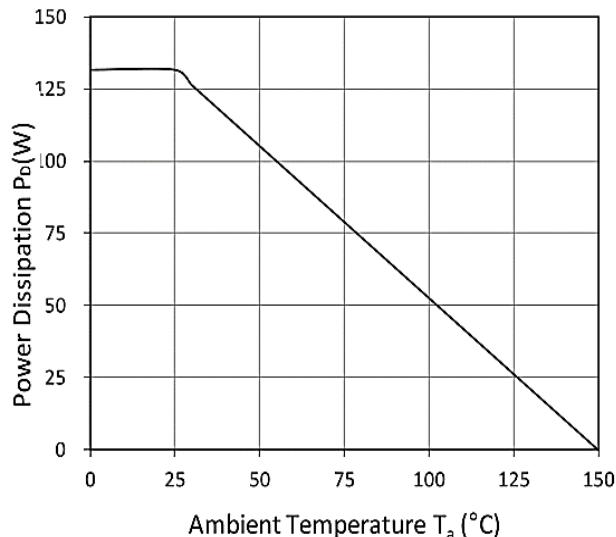
**100V N-Channel Enhancement Mode MOSFET**



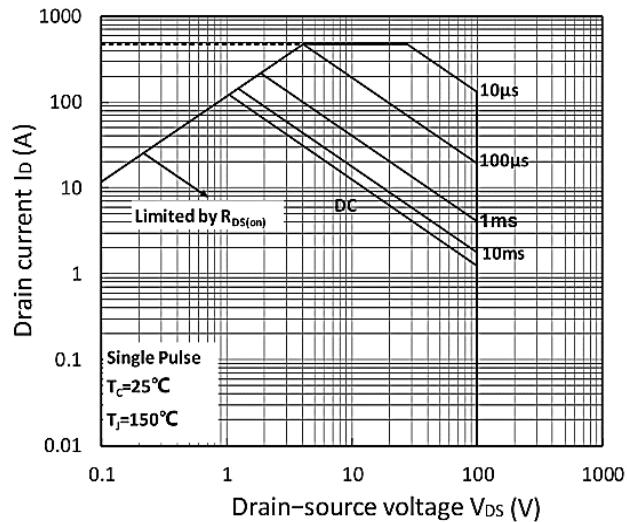
**Figure 7. Capacitance Characteristics**



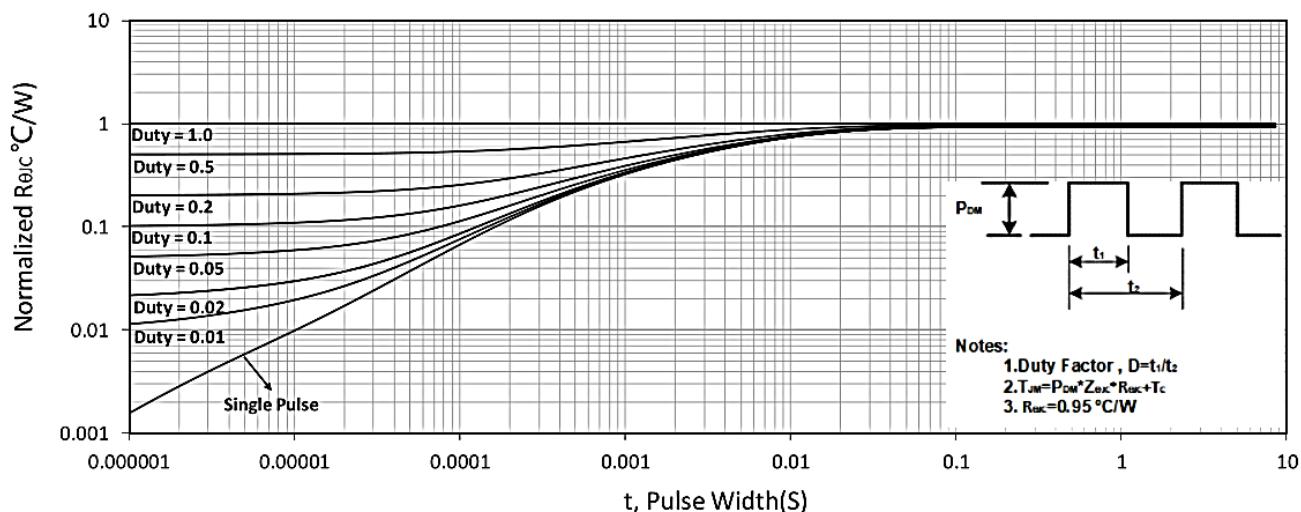
**Figure 8. Gate Charge Characteristics**



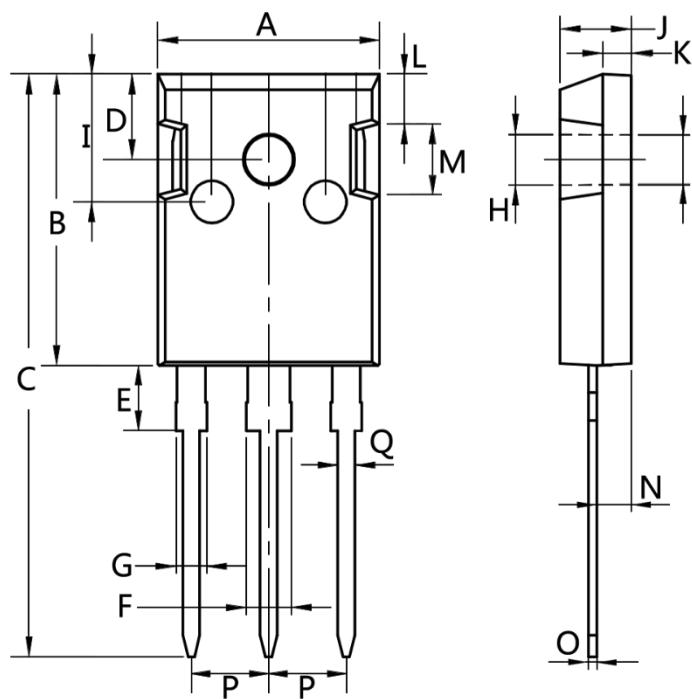
**Figure 9. Power Dissipation**



**Figure 10. Safe Operating Area**



**Figure 11. Normalized Maximum Transient Thermal Impedance**

**Package Mechanical Data-TO-247-3L**


Dim.	Min.	Max.
A	15.0	16.0
B	20.0	21.0
C	41.0	42.0
D	5.0	6.0
E	4.0	5.0
F	2.5	3.5
G	1.75	2.5
H	3.0	3.5
I	8.0	10.0
J	4.9	5.1
K	1.9	2.1
L	3.5	4.0
M	4.75	5.25
N	2.0	3.0
O	0.55	0.75
P	Typ 5.08	
Q	1.2	1.3